

CDRAM Code Information

S 8 X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : CDRAM (8)

3. Small Classification

S : SDRAM

4~5. Density, Refresh

31 : 4M, 1K/16ms

32 : 4M, 2K/32ms

6. Bank

2 : 2Bank

7. Interface, VDD, VDDQ

2 : LVTTL, 3.3V, 3.3V

8. Version

X : 1st Generation

A : 2nd Generation

9~10. Organization

01 : x1

08 : x8

16 : x16

11. " - "

12. Package Type (standard : AG1000)

C : CHIP BIZ

T : TSOP2

W : WAFER

Y : FBGA

13. Temp, Power

C : Commercial, Normal

14. Packing

B : Tube

U : Bulk

R : Tray

T : Tape & Reel

S : Tape & Reel Reverse

C : Chip Biz

D : Chip Biz (3 Inch tray)

E : Chip Biz (4 Inch tray)

F : Chip Biz (Reverse)

W : WF Biz Draft Wafer

X : WF Biz Full Cutting

3 : Tape & Reel (Halogen-Free PKG)

4 : Tray (Halogen-Free PKG)

5 : Tube (Halogen-Free PKG)

7 : Tape & Reel (Lead-Free PKG)

8 : Tray (Lead-Free PKG)

9 : Tube (Lead-Free PKG)

15. Speed (Wafer/Chip Biz= 0)

- SDRAM

1 : 10ns